电性参数

ǎ Ta=25 Absolute Maximum Rating(ta)

ǎ parameter	ỷ Value	ɣ Unit
w Power Dissipation	50	mW
ǁ Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse width	80	mA
h Forward current	20	mA
ẓ ƨ ỳ Electrostatic Discharge	2000	(ˋ ɬ : V
Operation Temperature Range	-40 ~ +85	
Ũ Storage Temperature Range	-40 ~ +85	
Lead Soldering Temperature	260 ≤ 6S	

光电参数 Ta=25 Optical-electrical parameter(ta=25)

ǎ parameter	ˆ Symbol	Test

包装（1）

Packaging (1)

载带 Belt and disk dimensions

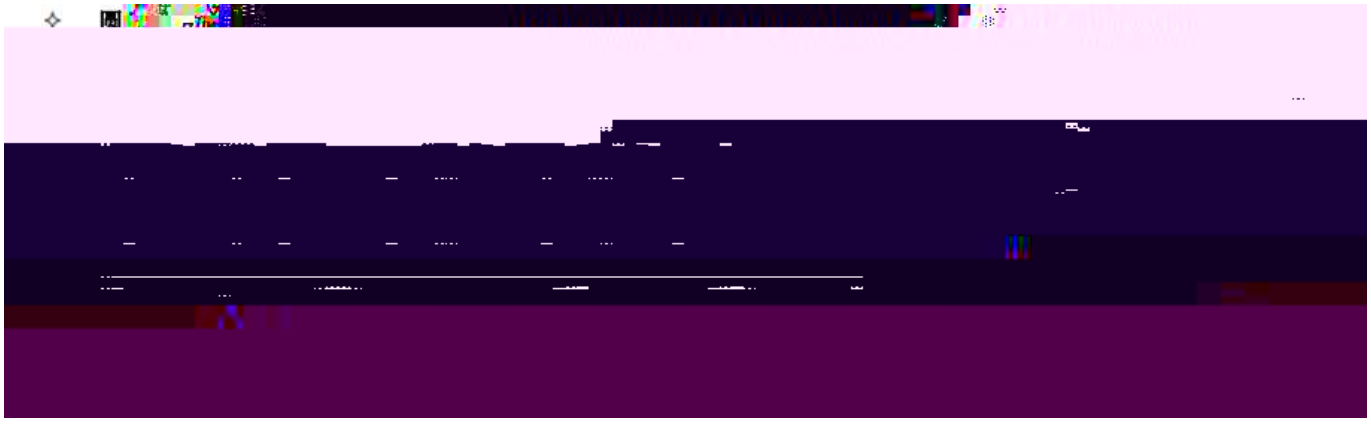
:

1. 丬 (mm)

1. Size unit is mm (mm).

2. 'E ±0.1mm

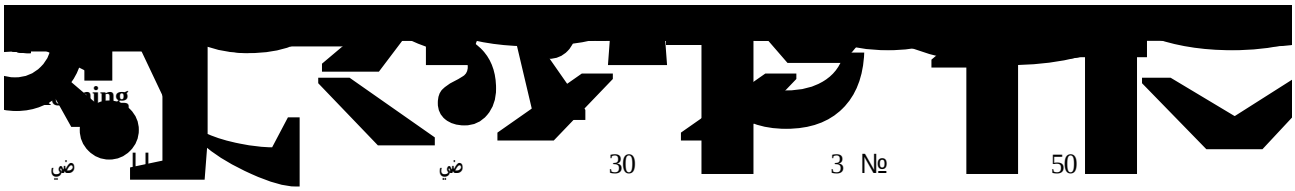
2. The dimensional tolerance is ± 0.1mm.



P

焊接指导（2）

Guideline for Soldering (2)



ضي 30 ضي 30 3 № 50

30

ὶ ϟ ╠ ὼ ϟ LED ἐ №

w 300W ϒ ↕ LED

ΐ ' ὼ ϒ LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50l for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Befor ι